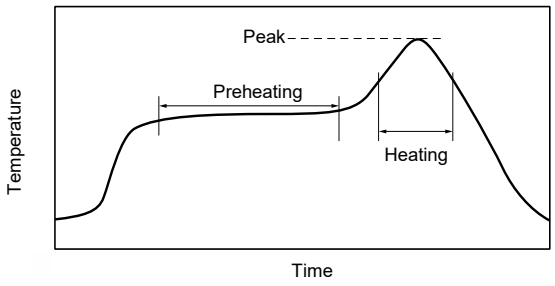
Recommended soldering conditions (Rectagular type)

Recommendations and precautions are described below.

● **Recommended soldering conditions for reflow**

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability be fore actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 ℃ to 160 ℃	60 s to 120 s
Main heating	Above 200 ℃	30 s to 40 s
Peak	235 ± 5 ℃	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 ℃ to 180 ℃	60 s to 120 s
Main heating	Above 230 ℃	30 s to 40 s
Peak	max. 260 ℃	max. 10 s

● **Recommended soldering conditions for flow**

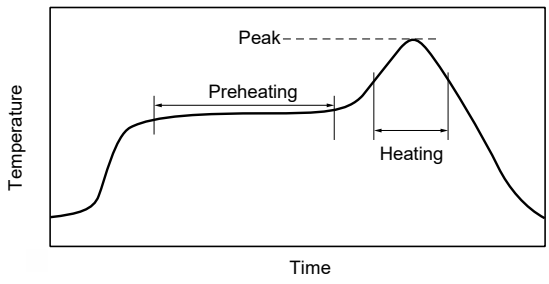
	For soldering		For lead-free soldering	
	Temperature	Time	Temperature	Time
Preheating	140 ℃ to 160 ℃	60 s to 120 s	150 ℃ to 180 ℃	60 s to 120 s
Soldering	245 ± 5 ℃	20 s to 30 s	max. 260 ℃	max. 10 s

Recommended soldering conditions (Chip resistor array / networks and Chip attenuator)

Recommendations and precautions are described below.

● **Recommended soldering conditions for reflow**

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability be fore actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 ℃ to 160 ℃	60 s to 120 s
Main heating	Above 200 ℃	30 s to 40 s
Peak	235 ± 5 ℃	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 ℃ to 180 ℃	60 s to 120 s
Main heating	Above 230 ℃	30 s to 40 s
Peak	max. 260 ℃	max. 10 s

● **Flow soldering**

We do not recommend flow soldering, because a solder bridge may form.
Please contact us regarding flow sol der ing of EXBA series.